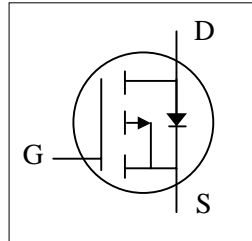
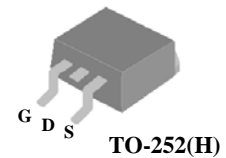


- ▼ Lower Gate Charge
- ▼ Simple Drive Requirement
- ▼ Fast Switching Characteristic
- ▼ RoHS Compliant & Halogen-Free



$BV_{DSS}$	-40V
$R_{DS(ON)}$	40m $\Omega$
$I_D$	-19.6A



## Description

XP4P040 series are innovated design and silicon process technology to achieve the lowest possible on-resistance and fast switching performance. It provides the designer with an extreme efficient device for use in a wide range of power applications.

The TO-252 package is widely preferred for all commercial-industrial surface mount applications using infrared reflow technique and suited for high current application due to the low connection resistance.

## Absolute Maximum Ratings @ $T_j=25^\circ\text{C}$ (unless otherwise specified)

Symbol	Parameter	Rating	Units
$V_{DS}$	Drain-Source Voltage	-40	V
$V_{GS}$	Gate-Source Voltage	+20	V
$I_D@T_C=25^\circ\text{C}$	Drain Current, $V_{GS}$ @ 10V	-19.6	A
$I_D@T_C=100^\circ\text{C}$	Drain Current, $V_{GS}$ @ 10V	-12.4	A
$I_{DM}$	Pulsed Drain Current <sup>1</sup>	-80	A
$P_D@T_C=25^\circ\text{C}$	Total Power Dissipation	25	W
$P_D@T_A=25^\circ\text{C}$	Total Power Dissipation <sup>4</sup>	2	W
$E_{AS}$	Single Pulse Avalanche Energy <sup>3</sup>	16.2	mJ
$T_{STG}$	Storage Temperature Range	-55 to 150	$^\circ\text{C}$
$T_J$	Operating Junction Temperature Range	-55 to 150	$^\circ\text{C}$

## Thermal Data

Symbol	Parameter	Value	Units
Rthj-c	Maximum Thermal Resistance Junction-case	5	$^\circ\text{C}/\text{W}$
Rthj-a	Maximum Thermal Resistance, Junction-ambient (PCB mount) <sup>3</sup>	62.5	$^\circ\text{C}/\text{W}$

**Electrical Characteristics @ $T_j=25^{\circ}\text{C}$  (unless otherwise specified)**

Symbol	Parameter	Test Conditions	Min.	Typ.	Max.	Units
$BV_{DSS}$	Drain-Source Breakdown Voltage	$V_{GS}=0V, I_D=-250\mu A$	-40	-	-	V
$R_{DS(ON)}$	Static Drain-Source On-Resistance <sup>2</sup>	$V_{GS}=-10V, I_D=-10A$	-	-	40	m $\Omega$
		$V_{GS}=-4.5V, I_D=-6A$	-	-	60	m $\Omega$
$V_{GS(th)}$	Gate Threshold Voltage	$V_{DS}=V_{GS}, I_D=-250\mu A$	-1	-	-3	V
$g_{fs}$	Forward Transconductance	$V_{DS}=-10V, I_D=-10A$	-	17	-	S
$I_{DSS}$	Drain-Source Leakage Current	$V_{DS}=-32V, V_{GS}=0V$	-	-	-1	$\mu A$
$I_{GSS}$	Gate-Source Leakage	$V_{GS}=\pm 20V, V_{DS}=0V$	-	-	$\pm 100$	nA
$Q_g$	Total Gate Charge	$I_D=-6A$	-	12	19.2	nC
$Q_{gs}$	Gate-Source Charge	$V_{DS}=-32V$	-	4.5	-	nC
$Q_{gd}$	Gate-Drain ("Miller") Charge	$V_{GS}=-4.5V$	-	4.5	-	nC
$t_{d(on)}$	Turn-on Delay Time	$V_{DS}=-20V$	-	10	-	ns
$t_r$	Rise Time	$I_D=-10A$	-	26	-	ns
$t_{d(off)}$	Turn-off Delay Time	$R_G=3.3\Omega$	-	37	-	ns
$t_f$	Fall Time	$V_{GS}=-10V$	-	38	-	ns
$C_{iss}$	Input Capacitance	$V_{GS}=0V$	-	1340	2144	pF
$C_{oss}$	Output Capacitance	$V_{DS}=-20V$	-	120	-	pF
$C_{rss}$	Reverse Transfer Capacitance	$f=1.0\text{MHz}$	-	80	-	pF
$R_g$	Gate Resistance	$f=1.0\text{MHz}$	-	8.5	17	$\Omega$

**Source-Drain Diode**

Symbol	Parameter	Test Conditions	Min.	Typ.	Max.	Units
$V_{SD}$	Forward On Voltage <sup>2</sup>	$I_S=-10A, V_{GS}=0V$	-	-	-1.2	V
$t_{rr}$	Reverse Recovery Time	$I_S=-10A, V_{GS}=0V,$	-	12	-	ns
$Q_{rr}$	Reverse Recovery Charge	$dI/dt=-100A/\mu s$	-	6	-	nC

**Notes:**

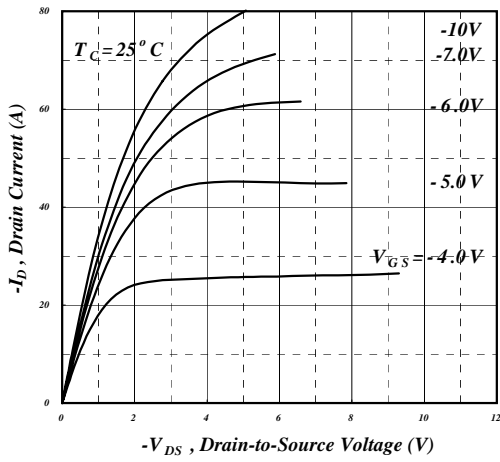
1. Pulse width limited by Max. junction temperature.
2. Pulse test
3. Starting  $T_j=25^{\circ}\text{C}$ ,  $V_{DD}=-30V$ ,  $L=0.1\text{mH}$ ,  $R_G=25\Omega$ ,  $V_{GS}=-10V$
4. Surface mounted on 1 in<sup>2</sup> copper pad of FR4 board

THIS PRODUCT IS SENSITIVE TO ELECTROSTATIC DISCHARGE, PLEASE HANDLE WITH CAUTION.

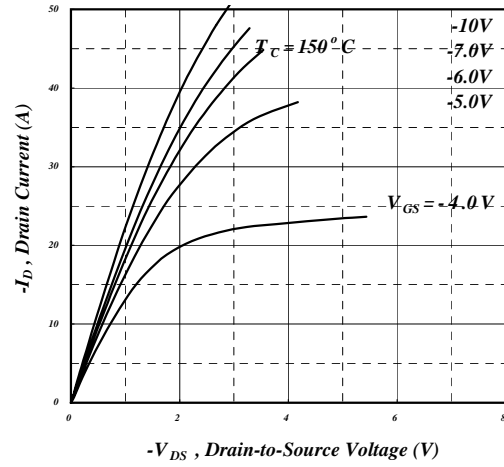
USE OF THIS PRODUCT AS A CRITICAL COMPONENT IN LIFE SUPPORT, AUTOMOTIVE OR OTHER SIMILAR SYSTEMS IS NOT AUTHORIZED.

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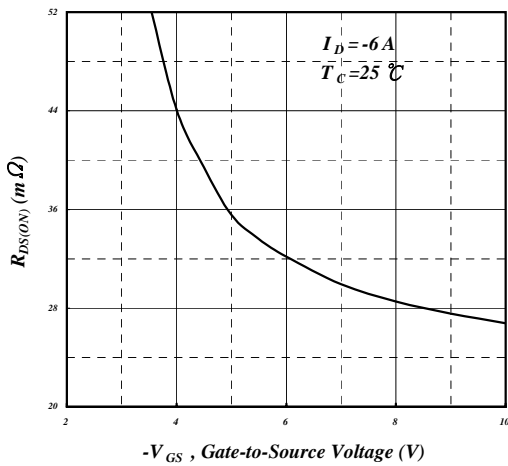
XSEMI RESERVES THE RIGHT TO MAKE CHANGES WITHOUT FURTHER NOTICE TO ANY PRODUCTS HEREIN TO IMPROVE RELIABILITY, FUNCTION OR DESIGN.



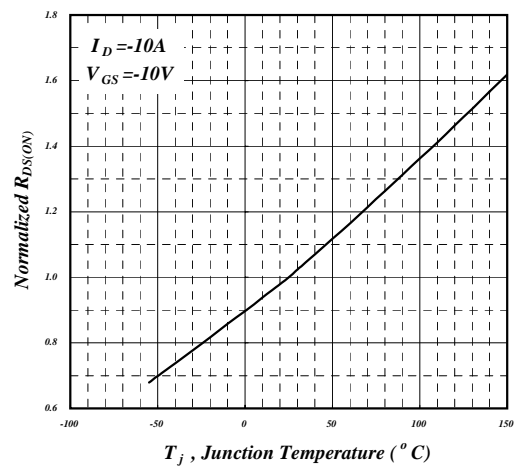
**Fig 1. Typical Output Characteristics**



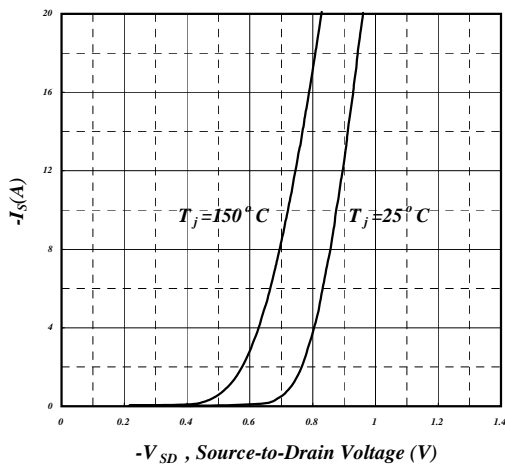
**Fig 2. Typical Output Characteristics**



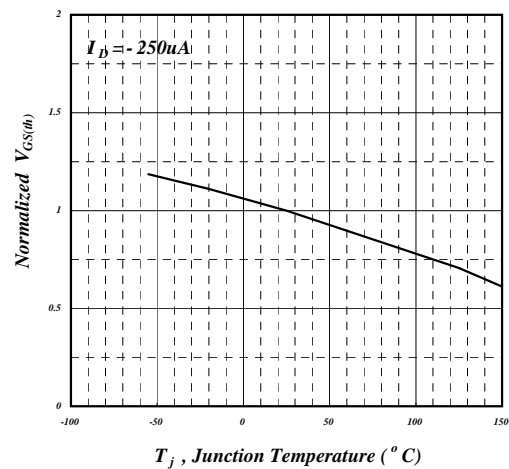
**Fig 3. On-Resistance v.s. Gate Voltage**



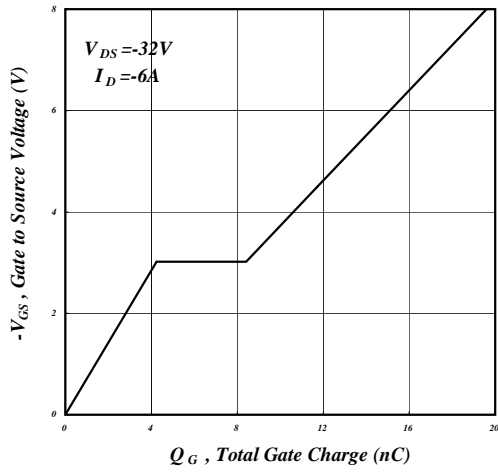
**Fig 4. Normalized On-Resistance v.s. Junction Temperature**



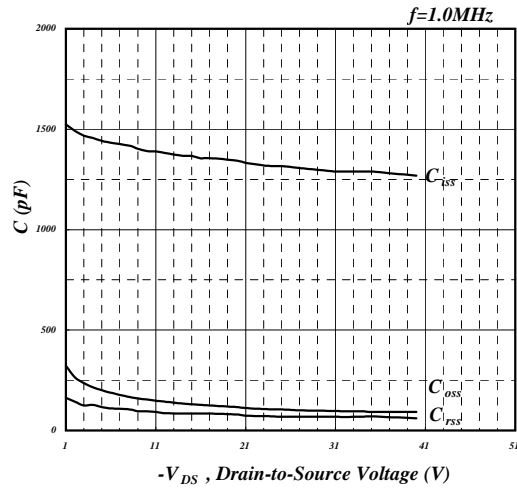
**Fig 5. Forward Characteristic of Reverse Diode**



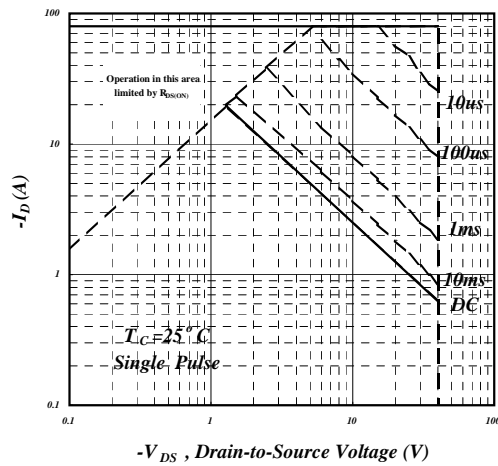
**Fig 6. Gate Threshold Voltage v.s. Junction Temperature**



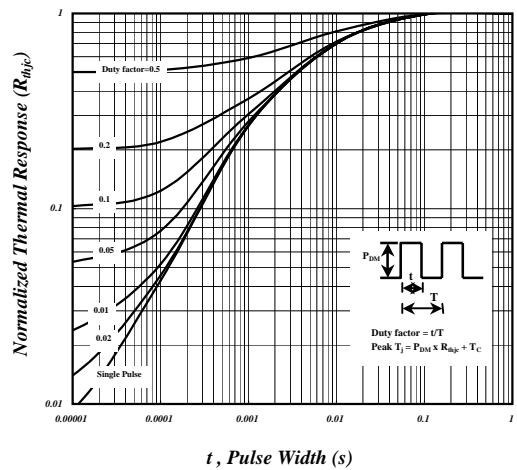
**Fig 7. Gate Charge Characteristics**



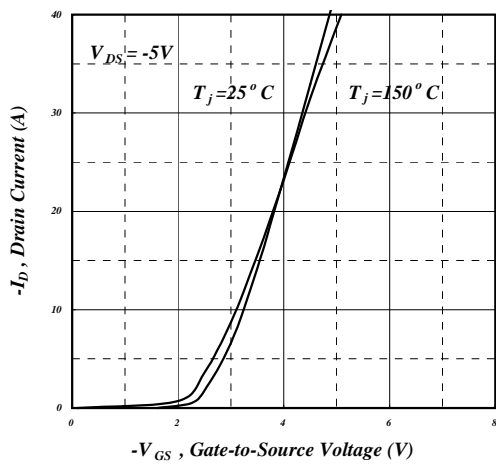
**Fig 8. Typical Capacitance Characteristics**



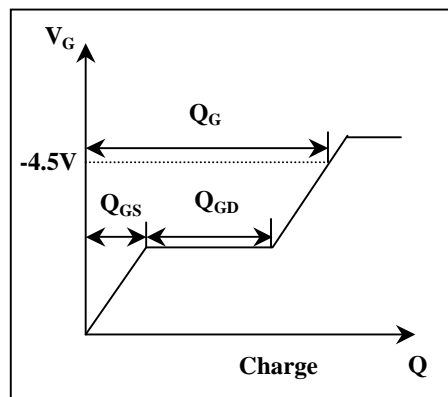
**Fig 9. Maximum Safe Operating Area**



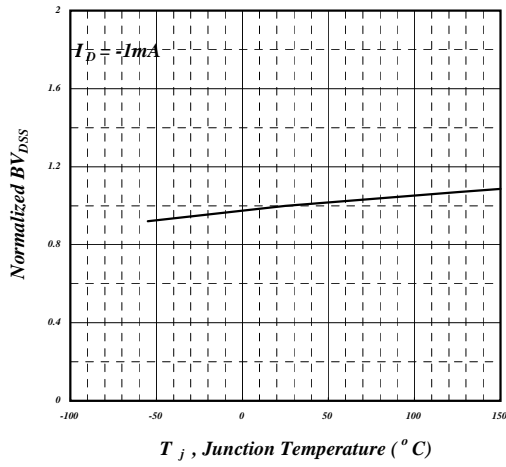
**Fig 10. Effective Transient Thermal Impedance**



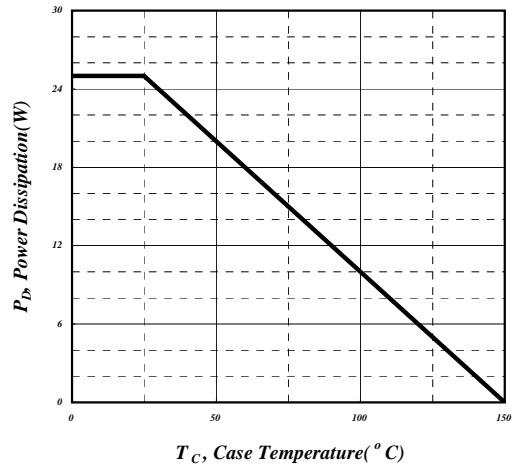
**Fig 11. Transfer Characteristics**



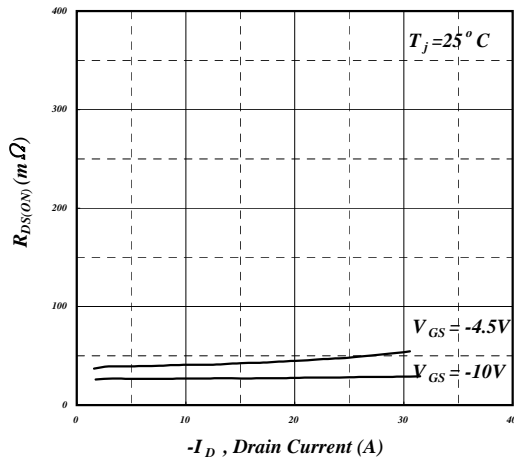
**Fig 12. Gate Charge Waveform**



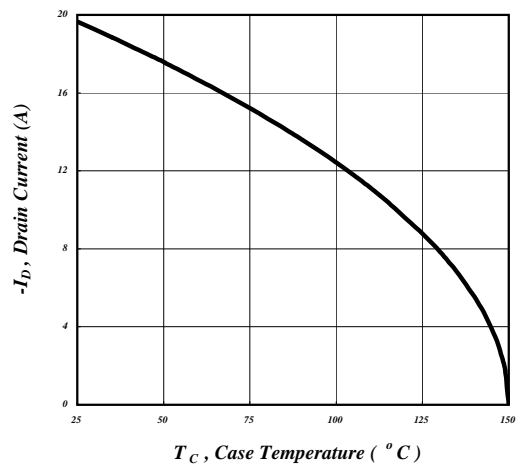
**Fig 13. Normalized  $BV_{DSS}$  v.s. Junction Temperature**



**Fig 14. Total Power Dissipation**



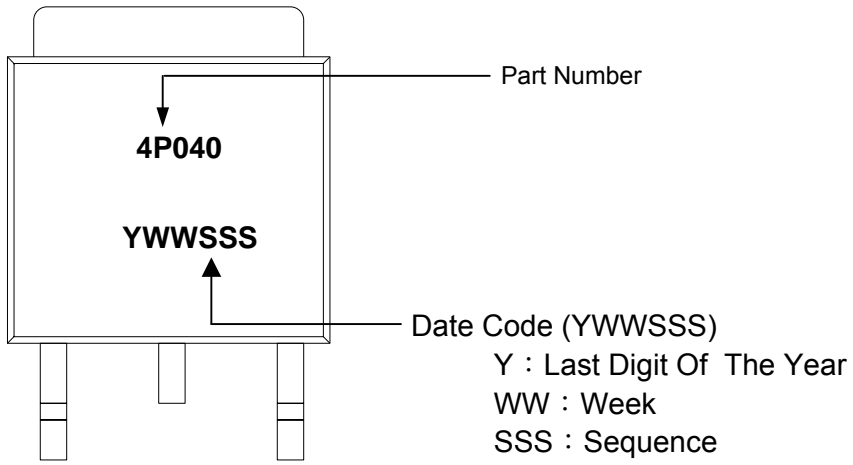
**Fig 15. Typ. Drain-Source on State Resistance**



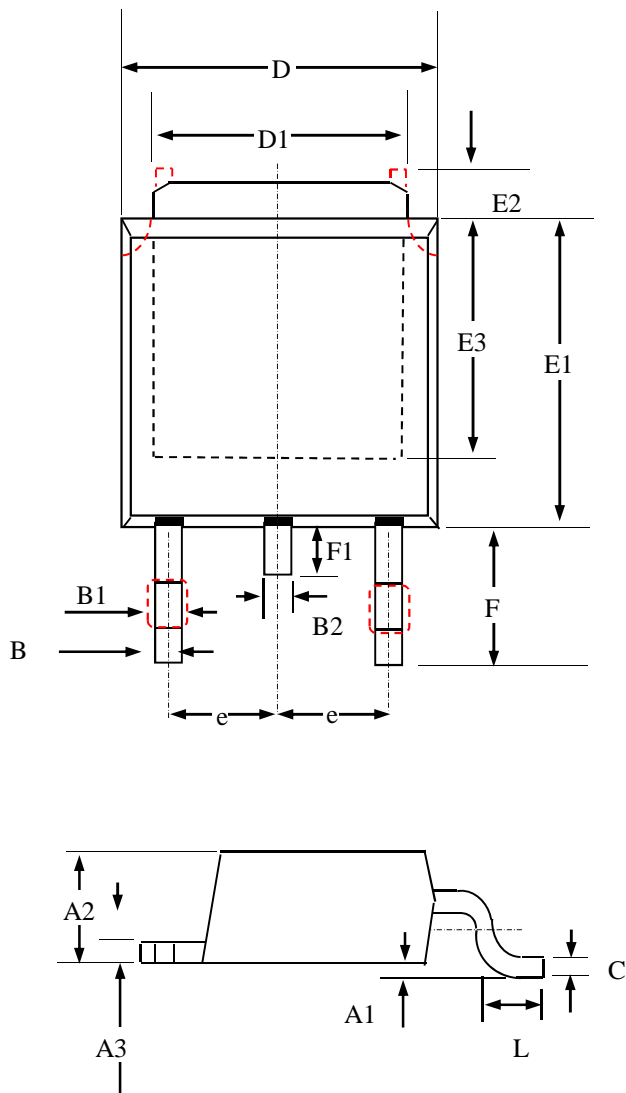
**Fig 16. Drain Current v.s. Case Temperature**

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**MARKING INFORMATION**



## Package Outline : TO-252



SYMBOLS	Millimeters		
	MIN	NOM	MAX
A2	2.18	2.30	2.40
A3	0.40	0.50	0.65
B	0.40	0.70	1.00
B1	0.50	0.85	1.20
D	6.00	6.50	6.80
D1	4.80	5.35	5.90
E3	4.00 (ref.)		
F	2.00	2.63	3.05
F1	0.50	0.85	1.20
E1	5.00	5.70	6.30
E2	0.50	1.10	1.80
e	2.3 (ref)		
C	0.35	0.525	0.70
A1	0.00	—	0.25
B2	—	—	1.25
L	0.90	1.34	1.78

- 1.All Dimensions Are in Millimeters.
- 2.Dimension Does Not Include Mold Protrusions.
3. Thermal PAD, Body and Pin contour is for reference, it may has little difference by option.

**TO-252 FOOTPRINT :**

